UNIKC Semiconductor

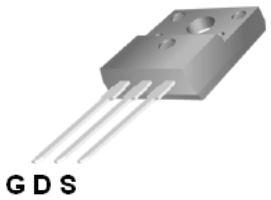
RoHS Compliant

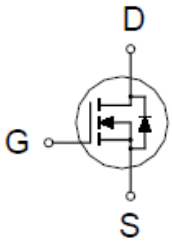
P0690ATF / P0690ATFS

N-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
900V	2.35Ω @V_{GS} = 10V	6A





TO-220F
TO-220FS

ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	900	V
Gate-Source Voltage		V_{GS}	±30	
Continuous Drain Current[2]	T_C = 25 °C	I_D	6	A
	T_C = 100 °C		3.5	
Pulsed Drain Current[1]		I_{DM}	18	
Avalanche Energy[3]		E_{AS}	45	mJ
Power Dissipation	T_C = 25 °C	P_D	52	W
	T_C = 100 °C		20	
Operating Junction & Storage Temperature Range		T_J, T_{STG}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.4	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

[1]Pulse width limited by maximum junction temperature.

[2]Ensure that the channel temperature does not exceed 150°C.

[3]V_{DD} = 50V ,L=10mH, starting T_J = 25°C.

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ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	900			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	2	3.4	4	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±30V			±100	nA
Gate Voltage Drain Current	I_{DSS}	V_{DS} = 480V, V_{GS} = 0V, T_C = 25 °C			1	μA
		V_{DS} = 400V, V_{GS} = 0V , T_C = 100 °C			100	
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 3A		2	2.35	Ω
Forward Transconductance[1]	g_{fs}	V_{DS} = 10V, I_D = 3A		6		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 25V, f = 1MHz		1610		pF
Output Capacitance	C_{oss}			89		
Reverse Transfer Capacitance	C_{rss}			9		
Total Gate Charge[2]	Q_g	V_{DD} = 720V, V_{GS} = 10V, I_D = 6A		34		nC
Gate-Source Charge[2]	Q_{gs}			10.5		
Gate-Drain Charge[2]	Q_{gd}			11		
Turn-On Delay Time[2]	$t_{d(on)}$	V_{DD} = 450V, I_D = 6A, R_G = 6Ω		80		nS
Rise Time[2]	t_r			190		
Turn-Off Delay Time[2]	$t_{d(off)}$			120		
Fall Time[2]	t_f			130		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)						
Continuous Current[3]	I_S				6	A
Forward Voltage[1]	V_{SD}	I_F = 6A, V_{GS} = 0V			1.4	V
Reverse Recovery Time	t_{rr}	I_F = 6A, dI_F/dt = 100A / μS		545		nS
Reverse Recovery Charge	Q_{rr}			3.6		μC

[1]Pulse test : Pulse Width ≤ 380 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

[3] Pulse width limited by maximum junction temperature.

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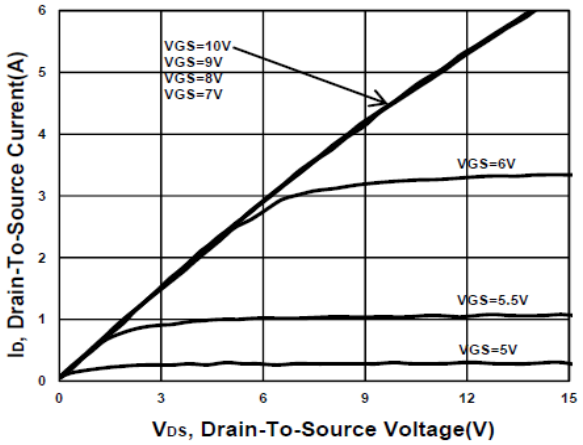
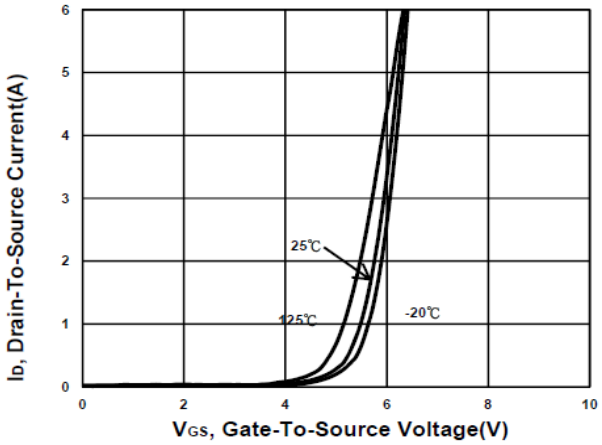
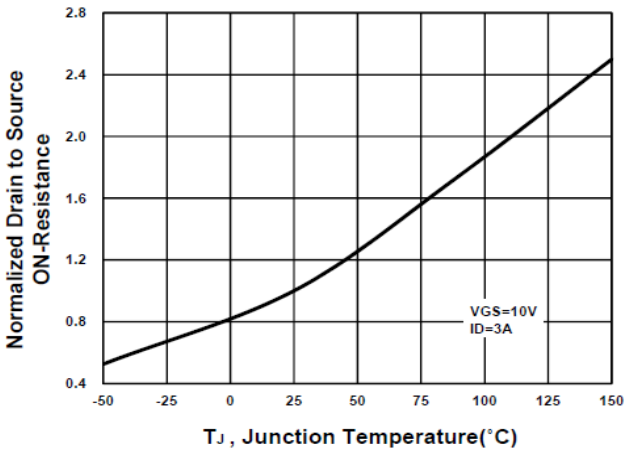
Output Characteristics



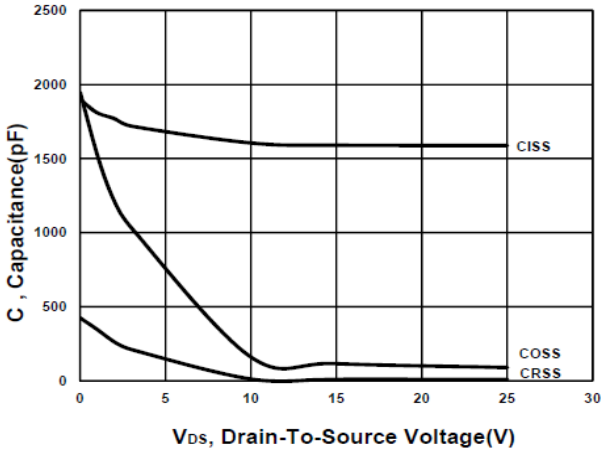
Transfer Characteristics



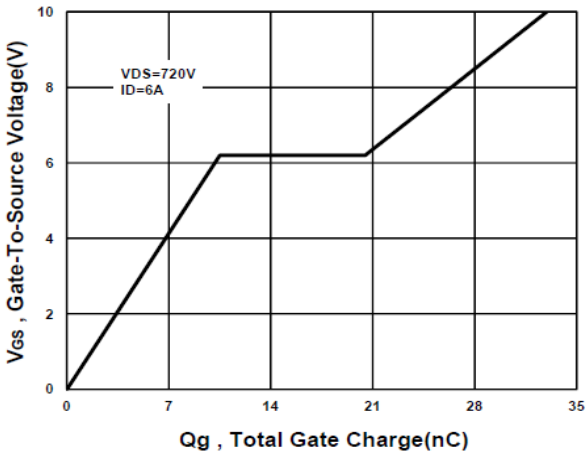
On-Resistance VS Temperature



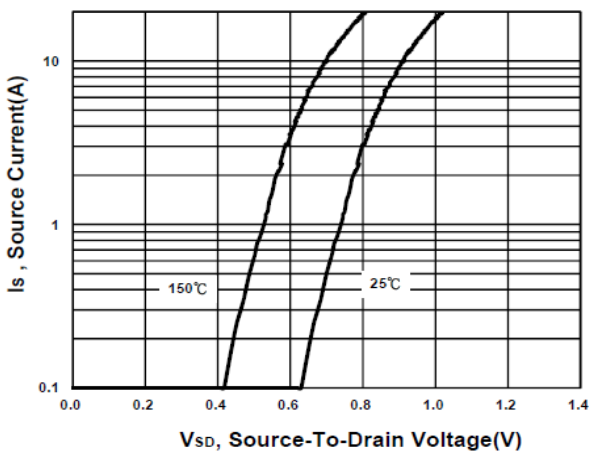
Capacitance Characteristic



Gate charge Characteristics



Source-Drain Diode Forward Voltage



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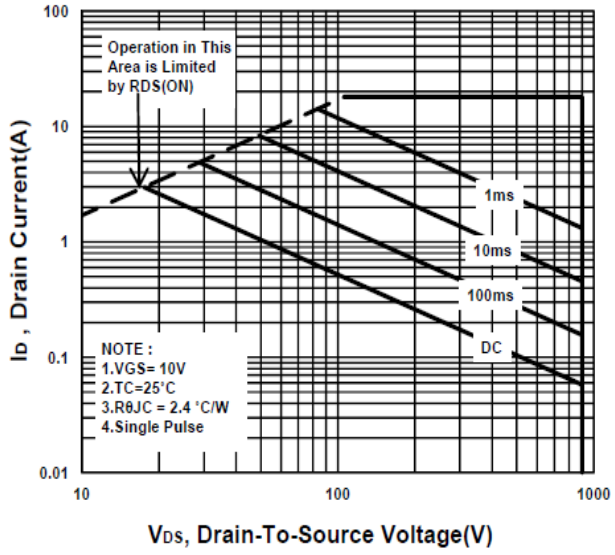
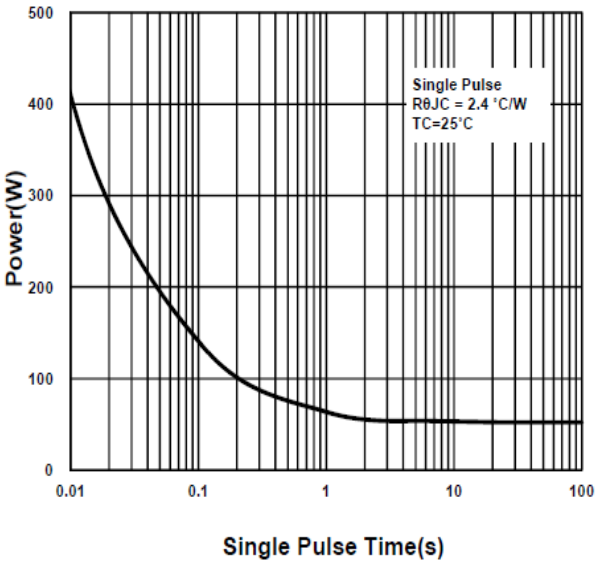
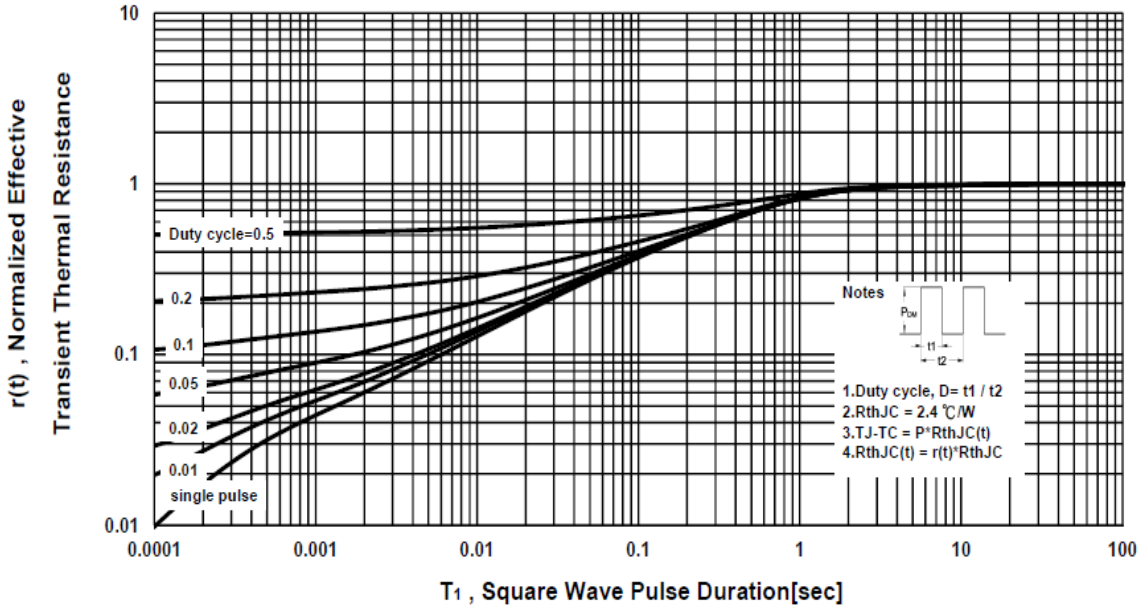
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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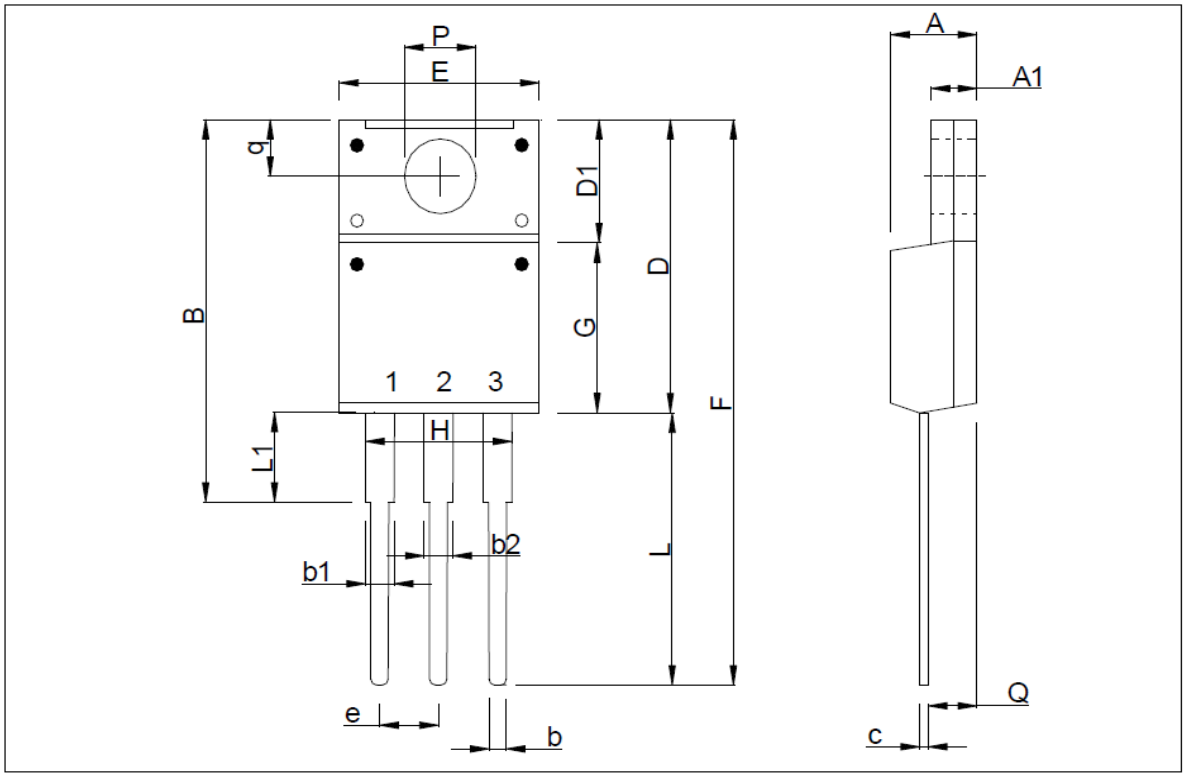
Package Dimension

TO-220F (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2		4.93	e	2.05	2.55	3.05
A1	2.34		3.1	F	27.45		30.6
B	17.77		20.3	G	7.72		9.3
b	0.6		1.05	H	6.1		7.1
b1	0.9	1.23	1.62	L	12.5		14.5
b2	0.6		1.9	L1	1.97		3.8
c	0.4		1.0	P	2.98		3.4
D	14.7		16.4	Q	2.1		2.96
D1	6.4		7.5	q	3.0		3.8
E	9.7		10.4				



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Package Dimension

TO-220FS (3-Lead) MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.2	4.7	4.93	e	2.05	2.54	3.05
A1	2.34	2.8	3.1	F	28.04		30.3
B	17.7		20.3	G	8.2	8.87	9.57
b	0.65	0.8	1.05	L	12.37		14.3
b1	0.9	1.3	1.5	L1	1.4	2.3	2.5
c	0.4	0.7	1.0	P	2.98	3.2	3.4
D	15.37		16.3	Q	2.1	2.6	2.96
D1	5.5		7.5	q	3.0	3.5	3.8
E	9.7	10.16	10.36